Features

- 150W (8x20us) PeakPulse Power
- Low Clamping Voltage
- SOD-323 Package
- RoHS Compliant
- MatteT in Lead finish (Pb-Free)
- Protect Onel/O or Power Line
- Meet IEC61000-4-2Level4:
  Contact Discharge>30kV
  Air Discharge>30 kV

PIN Diagram

Circuit Diagram

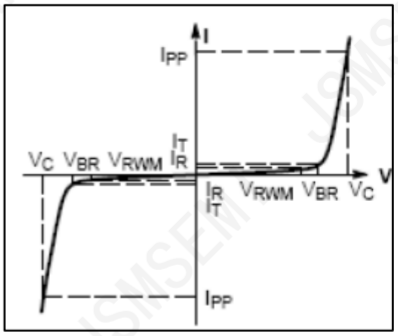
Applications

- SmartPhones
- LaptopComputers
- PortableElectronics

Maximum Ratings(Ta=25℃)

Symbol	Parameter	Value	Unit
TJ	JunctionTemperature	-55to+150	℃
TSTG	StorageTemperature	-55to+150	℃
IppMax	MaximumPeakPulseCurrent	10	A
PPK	PeakPulsePower	150	W

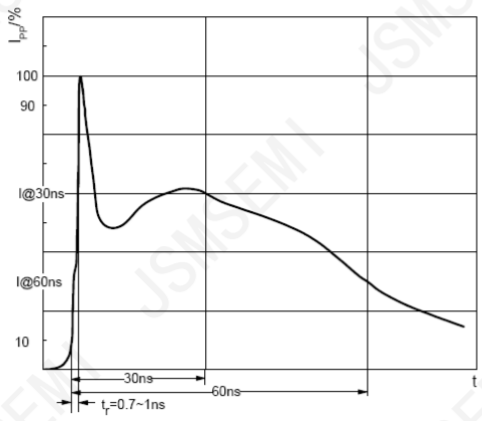
Symbol	Parameter
V_C	Clamping Voltage @ I_{PP}
I_{PP}	Peak Pulse Current
V_{BR}	Breakdown Voltage @ I_T
I_T	Test Current
I_R	Reverse Leakage Current @ V_{RWM}
V_{RWM}	Reverse Standoff Voltage



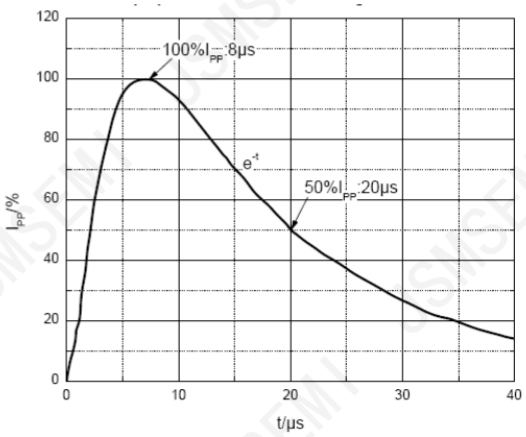
V-I characteristics for a Bi-directional TVS

Electrical Characteristics(Ta=25℃)

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
VRWM	Reverse Working Peak Voltage				5.0	V
VBR	Reverse Breakdown Voltage	IT = 1mA	6.2	7	8.5	V
IR	Reverse Leakage Current	VRWM = 5 . 0 V			1	μA
VC	Clamping Voltage	IPP = 1 A (8/20μs			9	V
VC	Clamping Voltage	)IPP = 1 0 A (8/20			15	V
Ipp	Peak Pulse Current	μs) ‘tp = 8/20μs			10	A
CJ	Capacitance	VR = 0V, f = 1MHz		25		pF

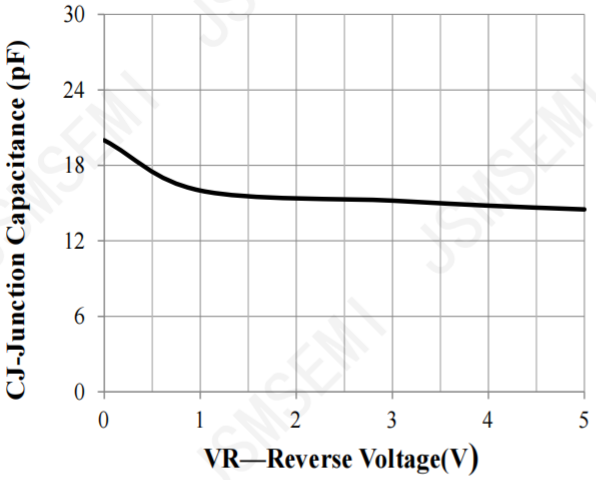


ESD pulse waveform according to IEC61000-4-2

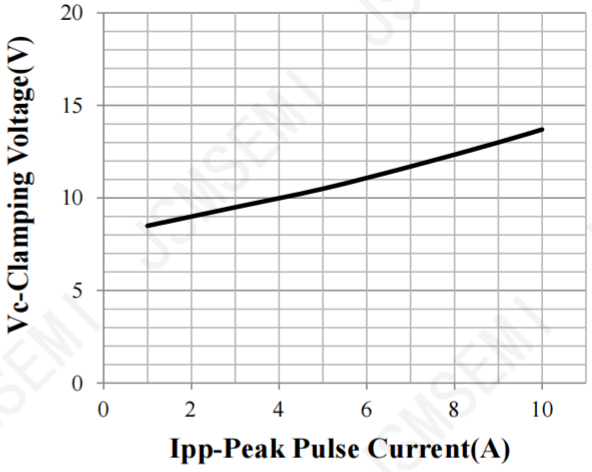


8/20μs pulse waveform according to IEC 61000-4-5

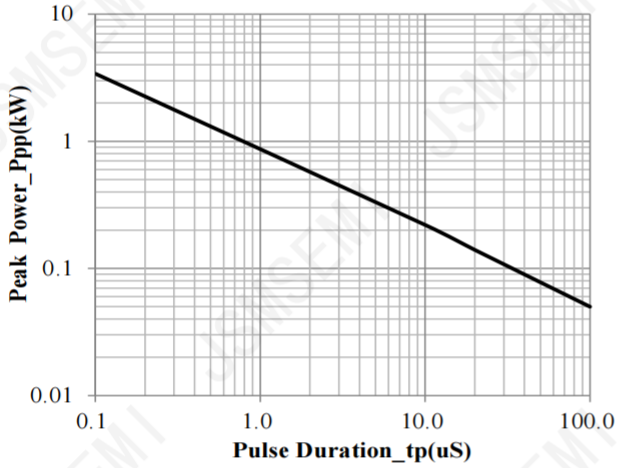
Typical Performance Characteristics (TA =25°C unless otherwise Specified)



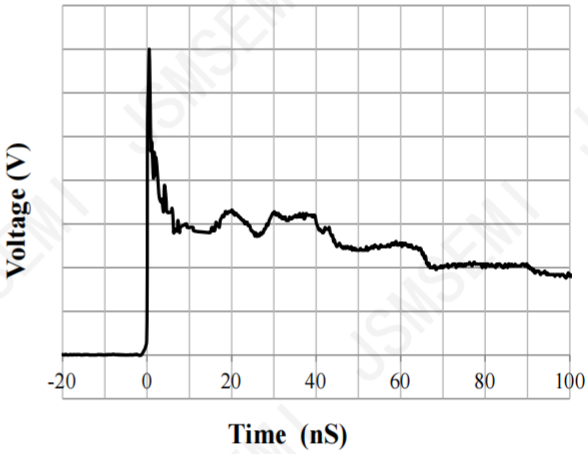
Junction Capacitance vs. Reverse Voltage



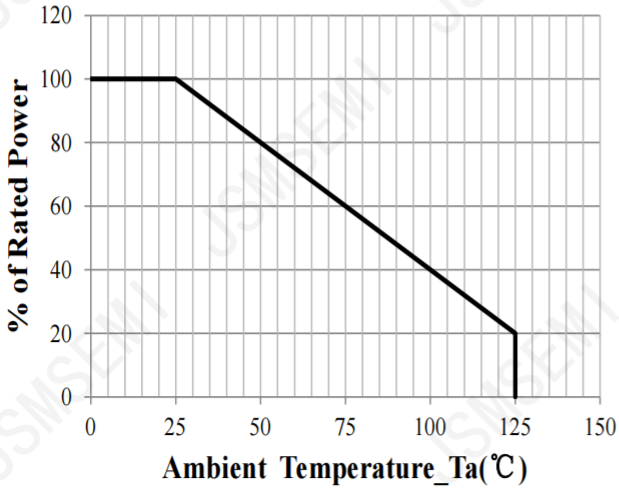
Clamping Voltage vs. Peak Pulse Current



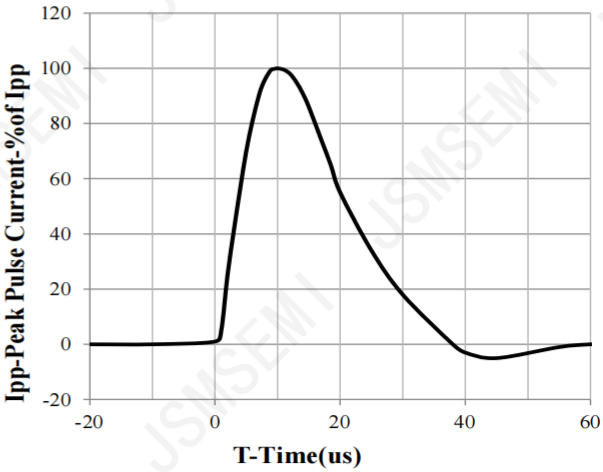
Peak Pulse Power vs. Pulse Time



IEC61000-4-2 Pulse Waveform

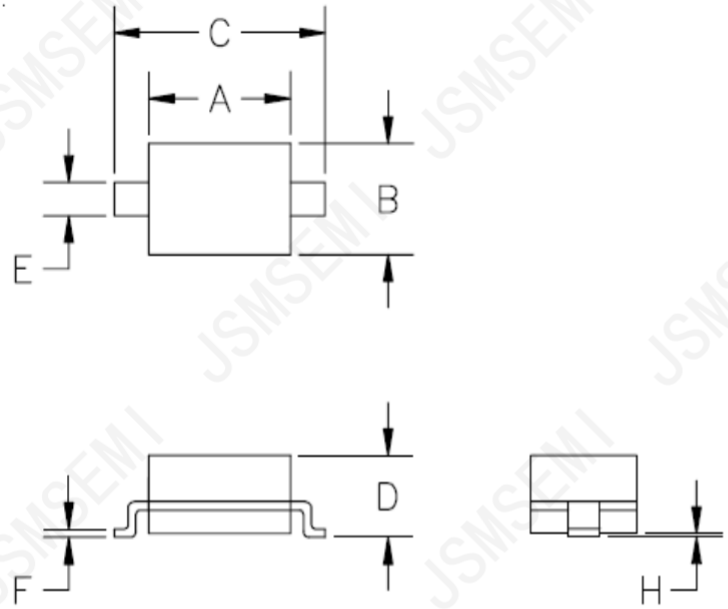


Power Derating Curve



8 X 20us Pulse Waveform

SOD-323 Dimension



DIMENSIONS					
DIM	INCHES		MM [1]		NOTE
	MIN	MAX	MIN	MAX	
A	.060	.071	1.5	1.8	–
B	.045	.054	1.2	1.4	–
C	.090	.107	2.3	2.7	–
D	–	.043	–	1.1	–
E	.012	.016	0.3	0.4	–
F	.004	.010	.10	.25	–
H	–	.004	–	.10	–

[1] CONTROLLING DIMENSION: MILLIMETERS

Revision History

Rev.	Change	Date
V1.0	Initial version	2/23/2024

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